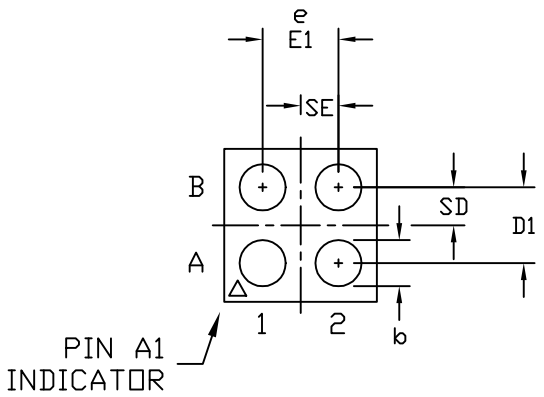


TOP VIEW

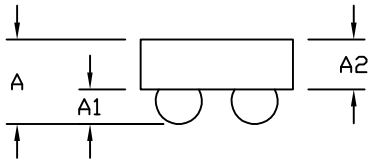
COMMON DIMENSIONS	
A	0.62+0.05-0.08
A1	0.29±0.02
A2	0.33 REF.
b	ø0.35±0.03
D1	0.50 BASIC
E1	0.50 BASIC
e	0.50 BASIC
SD	0.25 BASIC
SE	0.25 BASIC

PKG. CODE	VARIABLE DIMENSIONS		DEPOPULATED SOLDER BALLS
	D	E	
B4-1	1.00±0.05	1.00±0.05	NONE
B4-2	1.05±0.05	1.05±0.05	NONE
B4-3	1.10±0.05	1.10±0.05	NONE
B4-4	0.97±0.05	0.97±0.05	NONE

NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. PRODUCT MARKING: NUMBER OF CHARACTERS AND LINES VARY PER PRODUCT.



BOTTOM VIEW



SIDE VIEW

DALLAS SEMICONDUCTOR MAXIM

PROPRIETARY INFORMATION

TITLE:

PACKAGE OUTLINE, 2x2 UCSP

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0117	G	1/1